ASSOCIATION CONNECTION ELECTRONICS INDUSTRI	Material Compo © Copyright 2005. If international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Inform	nation															
Company name*			Company unique ID			J	Unique ID Authority					Response Date*				
onsemi											2025-06-08					
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*					
Product-Env-Stew	ards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			I	Phone - Representative*					Email - Representative*				
Product-Env-Stewards P			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Reques	ter Item Number	Mfr Item	fr Item Number Mfr Item Name  VD5C486NLT4G T6 40V DPAK expansion and update				Effective Date			ing Site	1	Veight*	UOM	Unit Type		
		NVD5C4			pansion and p	ortfolio	2025-06-08				350.99		mg	Each		
<b>Ianufacturing</b>	Process Informat	ion														
Terminal Plating / Grid Array Material			Cerminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperature Max Time at I		ne at Peak	Temperat	ire Num	ber of Reflow Cyc	eles				
Matte Tin (Sn) - annealed			CU Alloy 1			260	C 30			secon	is 3					
omments																
vel 1 - maximum	time at peak temperatu	re during sol	dering is 10-3	30 seconds					·		·		·	·		
or more informat	ion regarding material o	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated diphenyls of an applicable quantity limit, please indication in the graph of an applicable quantity limit, please indications. Supplier acknowledges that Company will we relied on information provided by others in a minimum and the Supplier agrees that, at a minimum and the Supplier enter into a written agreem source of the Supplier's liability and the Company of the Supplier's liability and the Supplier's liability and the Supplier's liability and the Company of the Supplier's liability and the Supplier's liabi	J 2011/65/EU and implemented by the laws of the Eyl ethers (each a "RoHS restricted substance") in exate below which, if any, RoHS exemption you belie les in this form using appropriate methods to ensure rely on this certification in determining the complian completing this form, and that Supplier may not ha, its suppliers have provided certifications regarding tent with respect to the identified part, the terms and impany's remedies for issues that arise regarding info cable to such part shall apply.	cess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- unce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certifications conditions of that agreement, including any warr	ove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	A	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65			Epoxy resin	proprietary data		9.7238	mg
			Supplier	Phenolic Resin	Proprietary Data		3.2412	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		9.7238	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		106.313	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Al	1.37	mg	Supplier	Aluminum (Al)	7429-90-5		1.37	mg